

CHIPQUIK® EXB-SN96.5AG3.0CU0.5-0.5LB

Datasheet revision 1.0

www.chipquik.com

Super Low Dross™ Solder Bar Sn96.5/Ag3.0/Cu0.5 0.5lb (227g) Extruded

Product Highlights

Extruded High Reliability Solder Bar

Manufactured Specifically for High Quality Electronics Manufacturing (EMS, ECM, OEMs)

Designed for Solder Pots, Wave Solder Machines and Selective Solder Machines

Chip Quik® Super Low Dross™ Solder Bar is Ideal for Through Hole and Surface Mount Soldering

High Purity



Specifications

Alloy: Sn96.5/Ag3.0/Cu0.5

Melting Point: 217-220°C (423-428°F)

Packaging: 0.5 lb (227 +/-20 g) bar (Ships bagged. To ensure weight tolerance is met: Full bar and/or fractional bar segments may be combined in each bag.)

Shelf Life: Indefinite

Purity

Element	IPC J-STD-006C	ChipQuik® Super Low Dross™ BARSN96.5AG3.0CU0.5
Silver (Ag)	0.100 %	3.000 %
Aluminum (Al)	0.005 %	< 0.005 %
Arsenic (As)	0.030 %	< 0.030 %
Gold (Au)	0.050 %	< 0.050 %
Bismuth (Bi)	0.100 %	< 0.100 %
Cadmium (Cd)	0.002 %	< 0.002 %
Copper (Cu)	0.080 %	0.500 %
Iron (Fe)	0.020 %	< 0.020 %
Indium (In)	0.100 %	< 0.100 %
Nickel (Ni)	0.010 %	< 0.010 %
Lead (Pb)	0.070 %	< 0.070 %
Tin (Sn)	0.250 %	96.500 %
Zinc (Zn)	0.003 %	< 0.003 %
Antimony (Sb)	0.200 %	< 0.200 %

Tolerances: +/-0.100% (Composition ≤ 1.000%), +/-0.200% (1.000% < Composition ≤ 5.000%), +/-0.500% (Composition > 5.000%)

Storage and Handling

Store in a dry non-corrosive environment.

Transportation

This product has no shipping restrictions.

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Compliant

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):

Yes

RoHS 3 Directive (EU) 2015/863:

Yes